

features

- 10-Bit, 25-MSPS, Analog-to-Digital Converter (ADC)
- Single Power Supply Operation, 2.7 V to 3.3 V
- Low Power: 95 mW at 2.7 V, Power-Down Mode: 1 mW
- Full-Channel Differential-Nonlinearity Error: $\leq \pm 0.5$ LSB Typical
- Full-Channel Integral-Nonlinearity Error: $\leq \pm 1.5$ LSB Typical
- Dual Input Modes: CCD and Video
- Programmable-Gain Amplifier (PGA) With 0-dB to 36-dB Gain Range (0.047 dB/Step) for CCD Mode, 0-dB to 12-dB Gain Range (0.047 dB/Step) for Video Mode

- Serial Interface for Register Configuration
- Programmable Black-Level and Offset Calibration
- Analog Gain Implementation With Specified No Missing Code, Even At High Gains
- Additional Digital-to-Analog Converters (DACs) for External Analog Setting
- Internal Reference Voltages
- Programmable Internal-Timing Signal Delays
- 48-Terminal TQFP Package

applications

- Digital Still Camera
- Digital Camcorder
- Digital Video Camera

description

The VSP1021 device is a highly-integrated monolithic analog-signal processor/digitizer designed to interface the area charge-coupled-device (CCD) sensors in digital-camera and camcorder applications. The VSP1021 device performs all the analog processing functions necessary to maximize the dynamic range, corrects various errors associated with the CCD sensor, and then digitizes the results with an on-chip, high-speed ADC. The key components of the VSP1021 device include:

- Input clamp circuitry and a correlated double sampler (CDS)
- Programmable-gain amplifier (PGA) with 0-dB to 36-dB gain range for CCD mode and 0-dB to 12-dB range for video mode
- Two internal DACs for automatic or programmable optical-black-level and offset calibration
- 10-bit, 25-MSPS pipeline ADC for CCD mode and a 28-MSPS ADC for video mode
- Parallel data port for easy microprocessor interface and a serial port for configuring internal control registers
- Two additional DACs for external system control
- Internal reference voltages

The VSP1021 device is designed using advanced CMOS process and operates from a single 3-V power supply with a normal power consumption of just 95 mW, and 1 mW in power-down mode.

High throughput rate, single 3-V operation, very-low-power consumption, and fully-integrated analog-processing circuitry make the VSP1021 device an ideal CCD and video-signal-processing solution for electronic video-camcorder applications.

This device is available in a 48-terminal TQFP package and is specified over an operating temperature range of -20°C to 75°C .

AVAILABLE OPTIONS

T _A	PACKAGE TQFP (PFB)
-20°C to 75°C	VSP1021PFB



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2004, Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
VSP1021PFB	ACTIVE	TQFP	PFB	48	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-20 to 75	VSP1021	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TRAY

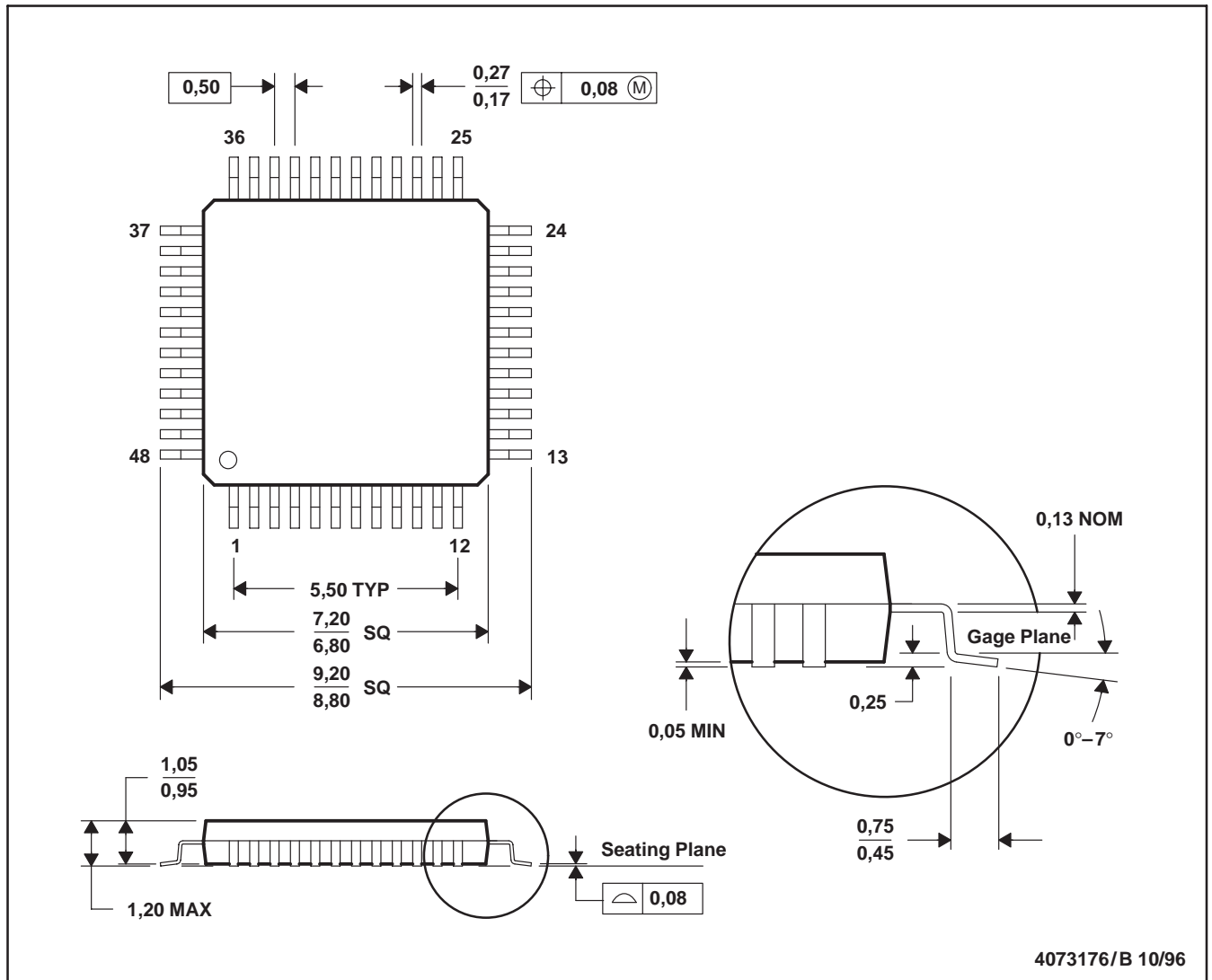

Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
VSP1021PFB	PFB	TQFP	48	250	10 x 25	150	315	135.9	7620	12.2	11.1	11.25

PFB (S-PQFP-G48)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026

PFB (S-PQFP-G48)



4209366/A 03/08

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2022, Texas Instruments Incorporated